

T-P-3 Series – Void Filler (0.50 – 5.00mm Shore 00 25/45)

DATASHEET



T-P-3 Series (0.50-5.00mm
Shore 00 25/45)

FEATURES

- Ultra-Soft with High Compressibility
- 1.5 W/mK Thermal Conductivity
- Low Thermal Impedance
- Naturally Tacky

APPLICATIONS

- Electronic Components: IC, CPU, MOS
- LED, Motherboards, Power Supplies, Heat Sinks, LCD-TV, Notebook PC, PC
- Telecom Devices, Wireless Hub, Automotive and Aerospace applications

PROPERTIES	TEST METHOD	UNIT	T-P-3 SERIES
Material	-	-	Ceramic Powder filled with Silicon Resin
Colour	Visual	-	Black
Thickness (±10%)	ASTM-D374	mm	0.50 – 5.00
Increments of 0.25mm/0.01inch		inch	0.02 – 0.20
Hardness (±10)	ASTM-D2240	Shore 00	25 (≥1.00mm) 45 (<1.00mm)
Thermal Conductivity	ASTM-D5470	W/mK	1.5
Flammability Rating	UL94 IEC 60695-11-10	-	UL94-V0
Dielectric Breakdown Voltage (1mm)	ASTM-D149	kV	≥10
Permittivity (1MHz)	ASTM-D150	-	6.54
Specific Gravity (±0.2)	ASTM-D792	g/cm ³	2.7
Working Temperature	EM344	°C	-40 to 200
Volume Resistance	ASTM-D257	Ohm-cm	10 ¹²
Tensile Strength	ASTM-D412-1998A	MPa	0.41

Note:

1. Customised shapes are available;
2. The above performance data is tested in an environment of 70% humidity, temperature 25°C.
3. This data is intended for reference purposes only. It is recommended that the material is tested to fully evaluate its performance ensuring it is fit for purpose.